


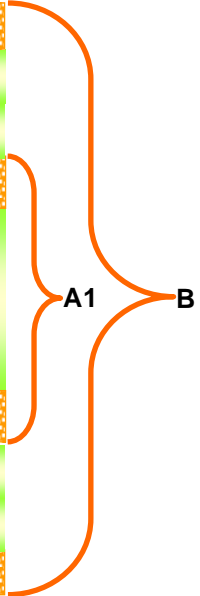


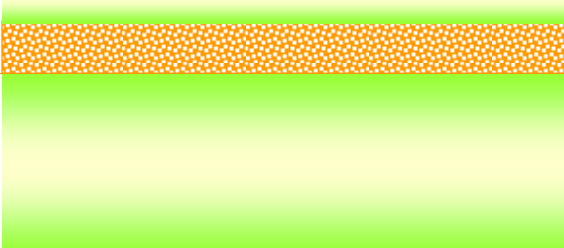




Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly	
Layer-1	35 μ	Copper			
	100 μ	Prepreg			(100 μ PrePreg-Type: 2125)
	100 μ	Prepreg			
Layer-2	70 μ	Copper			
	1360 μ	L-FR4			
Layer-3	70 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-99	35 μ	Copper			

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